Technical Data Sheet

Culver International Ltd
Dynaloy European Manufacturers Agent
Establishing Distributors and Maintaining
The European Network for Dynaloy, Inc.

DYNALOY
Engineered Chemistries
ISO 9001:2000

DYNASOLVE 185

Dynasolve 185 is a solvent for deflashing, depotting, deinking, and other epoxy removal. It contains a proprietary blend of ingredients that facilitate polymer removal and prevent the depositing of particles back onto a part.

General

Dynasolve 185 was developed so that a non-hazardous (by U.S. Department of Transportation definition) product was available for removing amine-cured epoxies. It is very effective, biodegradable, and has a versatility that allows it to be used in several applications as seen below. Dynasolve 185 does not contain phenol, chlorinated solvents, or strong acids and bases. Dynasolve 185 will not attack most metals used in electronic components including aluminum.

Applications

1. Dynasolve 185 is excellent for chemical deflashing of most plastics including Epoxy B-type materials.
2. It will disintegrate many epoxy-molded devices including UV-cured and amine-cured epoxies.
3. This solvent will remove many cured inks.
4. It is an effective solvent for removing molded epoxy residue from molds.
5. It is effective at softening and detackifying acrylic emulsions and other laminating or pressure-sensitive adhesives.

Specifications

Color:	Clear to Light Amber
Specific Gravity:	1.04
Boiling Point:	>369°F
Flash Point:	199°F

Directions For Use

DEFLASHING:

Heat Dynasolve 185 to 250-300°F under a vented hood. Immerse component for 15-30 minutes. Rinse with water; blow off any remaining flash with an air gun. May be run at 175-210°F for a longer length of time.

DEPOTTING/ DEINKING:

Immerse the component in Dynasolve 185, cover with a watch glass, and heat to 200°F under a vented hood. After depotting, allow the solution to cool, remove the device with metal tongs, and rinse with alcohol and water. If the epoxy does not disintegrate within one hour, raise the temperature to the boiling point and continue to heat. If there is no effect after 4 hours, discontinue heating, as the device is molded from Epoxy B or a polymer resistant to Dynasolve 185. For deinking, if Dynasolve 185 is not completely satisfactory, try Dynasolve 711 or 750. It may be necessary to suspend the component in solution so that the material removed will settle to the bottom of the container and not redeposit onto the component.

Caution and Warnings

Dynasolve 185 contains powerful organic solvents. It is harmful if inhaled or swallowed. Avoid breathing vapors or mist. Keep away from heat and flame. Avoid contact with eyes and skin. Wear gloves, safety glasses, and protective clothing when handling. Use with adequate ventilation. Refer to MSDS before use, for disposal, or additional safe handling.

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